

Memory Module Specifications

KHX18C9X3K4/16X

16GB (4GB 512M x 64-Bit x 4 pcs.)
 DDR3-1866 CL9 240-Pin DIMM Kit



SPECIFICATIONS

| | |
|--|-----------------------|
| CL(IDD) | 9 cycles |
| Row Cycle Time (tRCmin) | 49.5ns (min.) |
| Refresh to Active/Refresh Command Time (tRFCmin) | 160ns (min.) |
| Row Active Time (tRASmin) | 36ns (min.) |
| Maximum Operating Power | 2.400 W* (per module) |
| UL Rating | 94 V - 0 |
| Operating Temperature | 0° C to 85° C |
| Storage Temperature | -55° C to +100° C |

*Power will vary depending on the SDRAM used.

DESCRIPTION

Kingston's KHX18C9X3K4/16X is a kit of four 512M x 64-bit (4GB) DDR3-1866 CL9 SDRAM (Synchronous DRAM), 2Rx8 memory modules, based on sixteen 256M x 8-bit FBGA components per module. Each module kit supports **Intel® XMP** (Extreme Memory Profiles). Total kit capacity is 16GB. Each module kit has been tested to run at DDR3-1866 at a low latency timing of 9-11-9 at 1.65V. The SPDs are programmed to JEDEC standard latency DDR3-1333 timing of 9-9-9 at 1.5V. Each 240-pin DIMM uses gold contact fingers. The JEDEC standard electrical and mechanical specifications are as follows:

XMP TIMING PARAMETERS

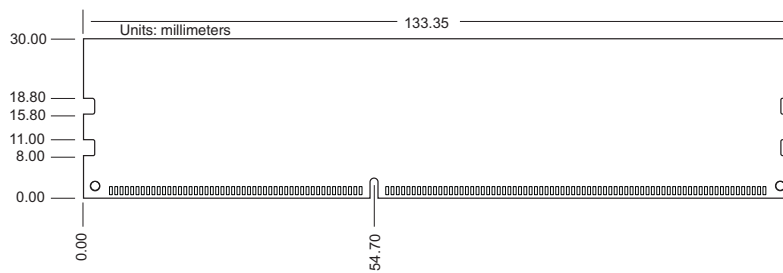
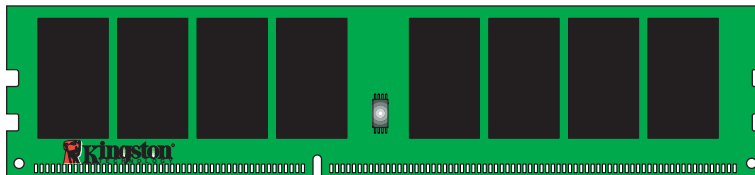
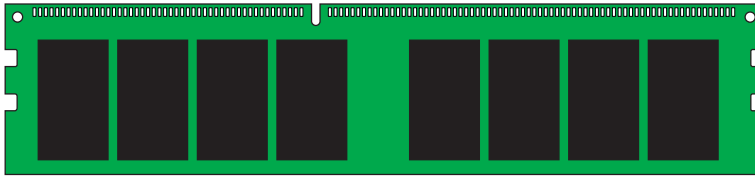
- JEDEC: DDR3-1333 CL9-9-9 @1.5V
- XMP Profile #1: DDR3-1866 CL9-11-9 @1.65V
- XMP Profile #2: DDR3-1600 CL9-9-9 @1.65V

FEATURES

- JEDEC standard 1.5V (1.425V ~ 1.575V) Power Supply
- VDDQ = 1.5V (1.425V ~ 1.575V)
- 667MHz fCK for 1333Mb/sec/pin
- 8 independent internal bank
- Programmable CAS Latency: 9, 8, 7, 6
- Programmable Additive Latency: 0, CL - 2, or CL - 1 clock
- Programmable CAS Write Latency(CWL) = 7 (DDR3-1333)
- 8-bit pre-fetch
- Burst Length: 8 (Interleave without any limit, sequential with starting address "000" only), 4 with tCCD = 4 which does not allow seamless read or write [either on the fly using A12 or MRS]
- Bi-directional Differential Data Strobe
- Internal(self) calibration : Internal self calibration through ZQ pin (RZQ : 240 ohm ± 1%)
- On Die Termination using ODT pin
- Average Refresh Period 7.8us at lower than TCASE 85°C, 3.9us at 85°C < TCASE ≤ 95°C
- Asynchronous Reset
- PCB : Height 1.18" (30mm) double sided component

Continued >>

MODULE DIMENSIONS



MODULE WITH HEAT SPREADER



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All Kingston products are tested to meet our published specifications. Some motherboards or system configurations may not operate at the published HyperX memory speeds and timing settings. Kingston does not recommend that any user attempt to run their computers faster than the published speed. Overclocking or modifying your system timing may result in damage to computer components.